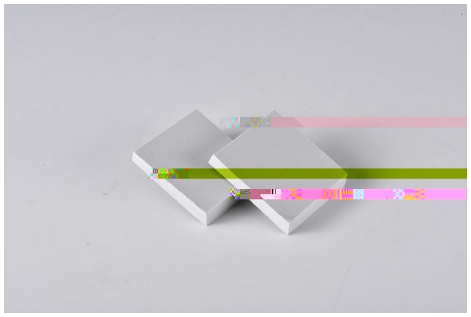
ThermalTSP0060-37

LDS A 2026.01



Thermal TSP0060-37

Thermal TSP0060-37 is a kind of silicone-based gap pad material with both thermal conductive and heat storage functionality. The product can be customized to different dimension based on terminal application scenarios, which has good prospect to be used in compact intelligent terminal applications.

Features

- High Enthalpy
- Good Mechanical Strength
- Excellent Processing Performance
- Excellent Reliability

Applications

- Action Camera
- Smart Watch / Phone
- /
- Virtual Reality
- Unmanned Aerial Vehicle

Property	Typical Value	Unit	Test Method
Color			
		J/cm^3	ASTM D3418
Phase Change Temperature	37	℃	ASTM D3418
Density	1.6	g/cm^3	ASTM D792
Hardness Shore A	70	—	ASTM D2240
Temperature Range	-40 - 100	℃	—
RoHS Compliance	YES	—	—
Shelf Life	12	month	25±5℃, 50% RH

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.